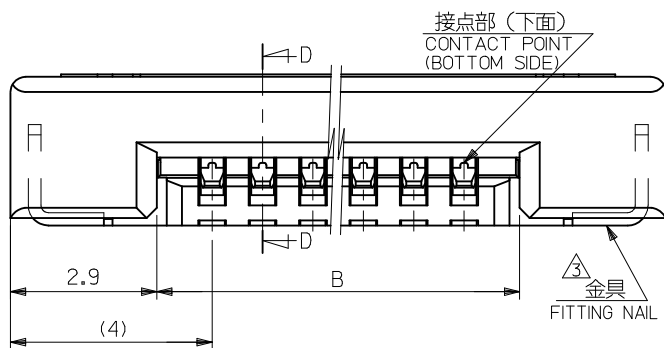
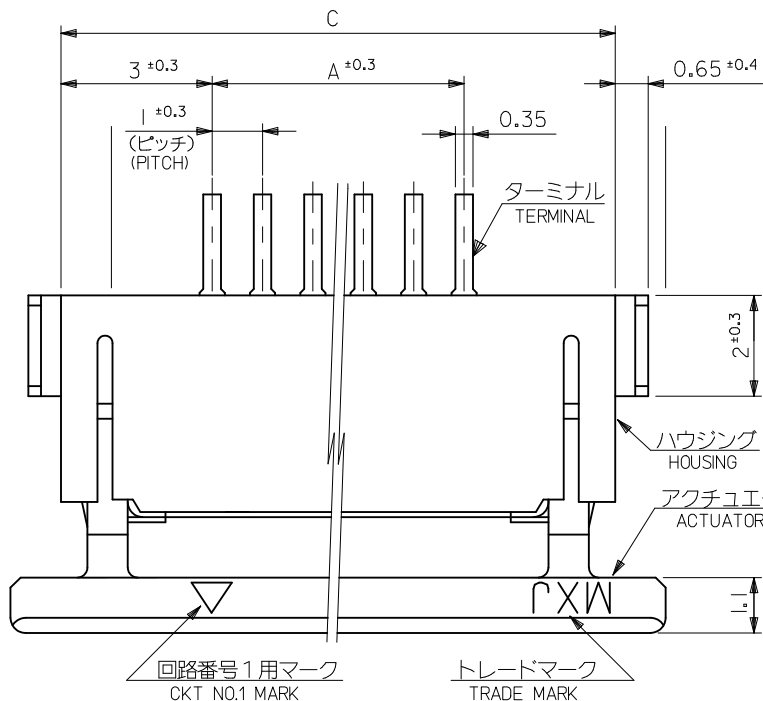
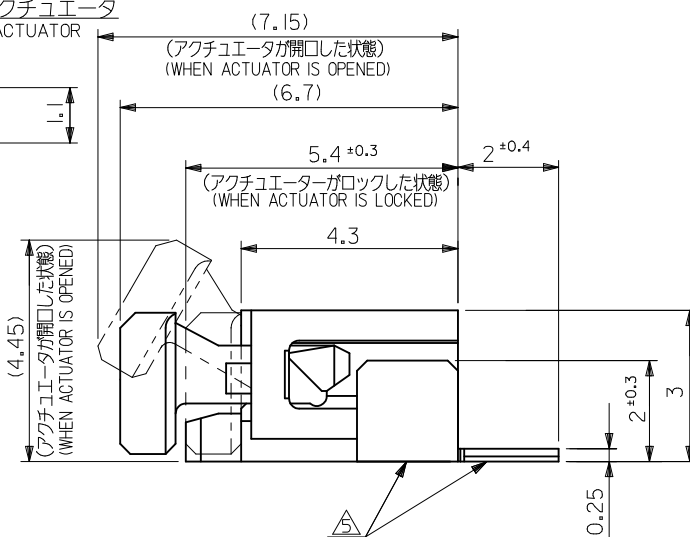


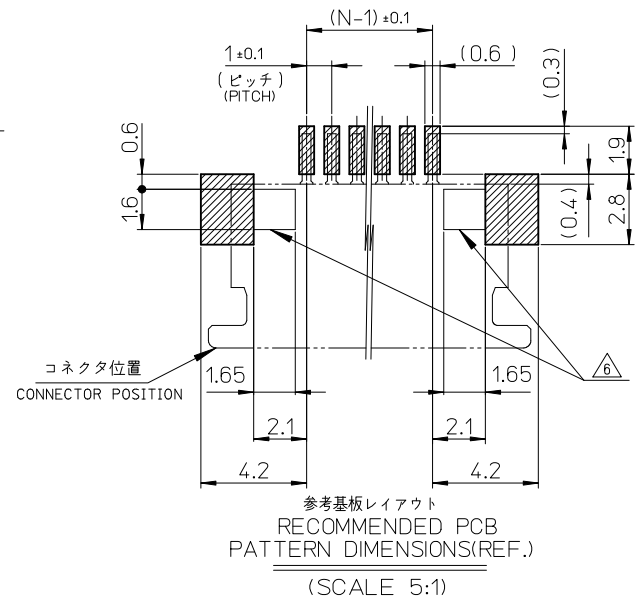
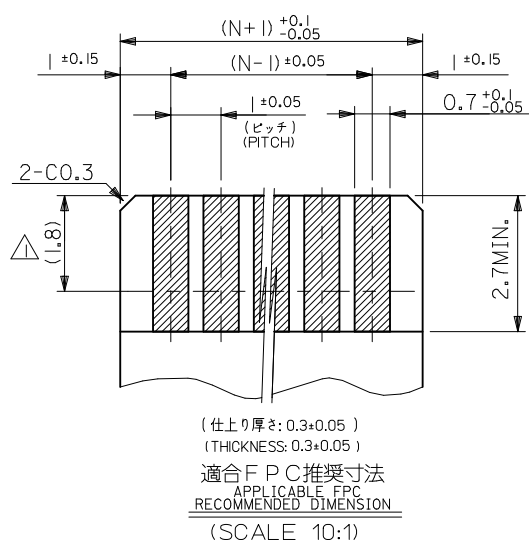
SECT.D-D



35	31.2	29	52271-3069	30
34	30.2	28	52271-2969	29
33	29.2	27	52271-2869	28
32	28.2	26	52271-2769	27
31	27.2	25	52271-2669	26
30	26.2	24	52271-2569	25
29	25.2	23	52271-2469	24
28	24.2	22	52271-2369	23
27	23.2	21	52271-2269	22
26	22.2	20	52271-2169	21
25	21.2	19	52271-2069	20
24	20.2	18	52271-1969	19
23	19.2	17	52271-1869	18
22	18.2	16	52271-1769	17
21	17.2	15	52271-1669	16
20	16.2	14	52271-1569	15
19	15.2	13	52271-1469	14
18	14.2	12	52271-1369	13
17	13.2	11	52271-1269	12
16	12.2	10	52271-1169	11
15	11.2	9	52271-1069	10
14	10.2	8	52271-0969	9
13	9.2	7	52271-0869	8
12	8.2	6	52271-0769	7
11	7.2	5	52271-0669	6
10	6.2	4	52271-0569	5
9	5.2	3	52271-0469	4
C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	CIRCUITS
52271-**-29			CONNECTOR SERIES NO.	

REVISED EC NO: J2012-1390 DRWN:K.NAGUMO CHKD:K.TAKAHASHI APPR:K.MORIKAWA	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION			
				MM ONLY		10:1	METRIC				
		10 UNDER	± 0.2	DRAWN BY	DATE	TITLE 1.0 FPC CONN ZIF SMT (BOTTOM CONTACT) -LEAD FREE- molex					
		10 OVER 30 UNDER	± 0.25	CHECKED BY	DATE						
		30 OVER	± 0.3	APPROVED BY	DATE						
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.					SHEET NO.
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-52271-038					1 OF 2
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									

10 9 8 7 6 5 4 3 2 1



注記 NOTES

- △ 接点部までの嵌合長さ。
LENGTH TO CONTACT POINT.
2. 使用材料 MATERIAL
- ハウジング : 46 NYLON, UL94V-0
HOUSING
- アクチュエータ : PPS, UL94V-0
ACTUATOR
- ターミナル : リン青銅 (t=0.25)
TERMINAL PHOSPHOR BRONZE (t=0.25)
- メッキ : 接点部: 金メッキ : 0.1 MICROMETER MIN.
PLATING CONTACT PORTION : GOLD PLATING : 0.1 MICROMETER MIN.
- メッキ : 半田付部: 錫メッキ : 1.0 MICROMETER MIN.
PLATING SOLDERING PORTION : TIN PLATING : 1.0 MICROMETER MIN.
- メッキ : 下地: ニッケルメッキ : 1.0 MICROMETER MIN.
PLATING UNDER PLATING : NICKEL PLATING : 1.0 MICROMETER MIN.
- 金具 : 銅合金 (t=0.25)
FITTING NAIL CUPPER ALLOY (t=0.25)
- 金具 : メッキ: 錫メッキ : 1.0 MICROMETER MIN.
FITTING NAIL PLATING : TIN PLATING : 1.0 MICROMETER MIN.
- 金具 : 下地: ニッケルメッキ : 1.0 MICROMETER MIN.
FITTING NAIL UNDER PLATING : NICKEL PLATING : 1.0 MICROMETER MIN.
- △ 3. パターンはくり止め用金具
FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B. PATTERN.
4. エンボステープ梱包時は、アクチュエータがロックした状態とする。
IN THE PACKAGE, ACTUATOR OF PART NO.54550-***29 SHOULD BE LOCKED.
- △ 5. テール及び金具の平坦度は、0.15 以下とする。
TAIL AND NAIL COPLANARITY TO BE 0.15 MAXIMUM.
- △ 6. パターン書き込み禁止エリア
NO FOOT PRINT AREA.

FPC について :

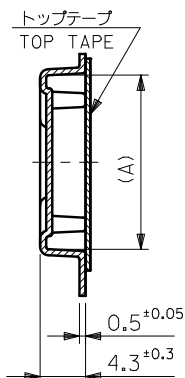
- 打抜き方向は、導体側から補強板側を推奨致します。
- 補強フィルム材質は、ポリイミドを推奨致します。
- 接着剤は、熱硬化接着剤を推奨致します。

ABOUT FPC :

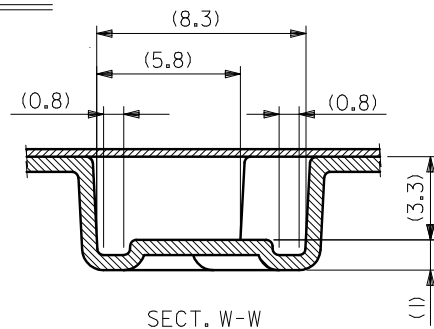
- RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE
- RECOMMENDED MATERIAL : STIFFENER FILM : POLYIMIDE BONDING AGENT : THERMOSETTING BONDING AGENT

REVISED EC NO: J2012-1390 DRAWN:KAGUMO 2012/05/10 CHKD:K.TAKAHASHI 2012/05/10 APPR:K.MORI/KAWA 2012/05/17	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE		
				MM ONLY		---	METRIC	PROJECTION		
		10 UNDER	± 0.2	DRAWN BY M.UMEDA	DATE 2005/03/08	TITLE 1.0 FPC CONN ZIF SMT (BOTTOM CONTACT) -LEAD FREE-				
		10 OVER 30 UNDER	± 0.25	CHECKED BY K.TOYODA	DATE 2005/03/08					
		30 OVER	± 0.3	APPROVED BY N.UKITA	DATE 2005/03/08	molex				
		ANGULAR ±3 °		MATERIAL NO.						
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1		SD-52271-038		2 OF 2			
REV		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

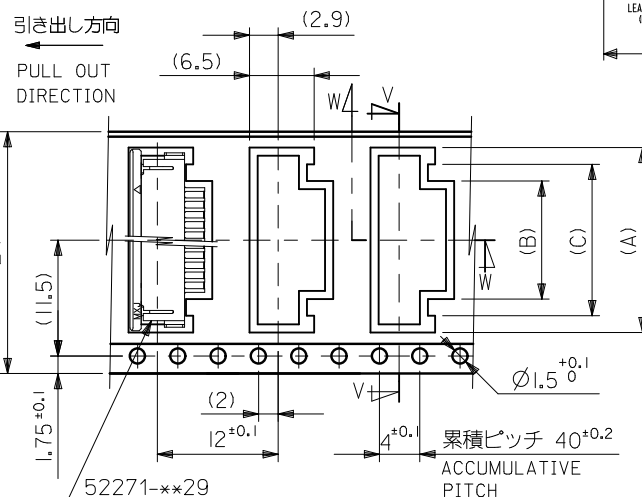
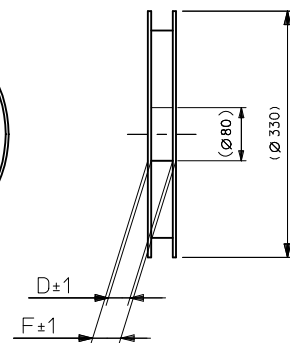
DETAIL "E"



SECT. V-V



SECT. W-W

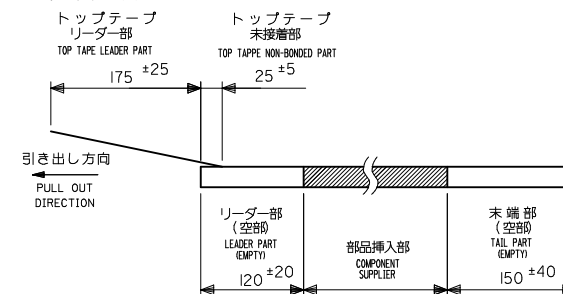


NOTES

l. 製品番号 52271-**29 の梱包状態はアクチュエータがロックした状態とする。
詳細寸法については 図面 SD-52271-038 を参照下さい。
IN THE PACKAGE, AUTUATOR OF PART NO. 52271-**29 SHOULD BE LOCKED
RE DETAILED DIMENSIONS, SEE SD-52271-038.

2. 梱包数量: 1000個/リール
NUMBER OF CONNECTORS: 1000 PCS/REEL

3. リードテープ長さ LEAD TAPE LENGTH



4. カバーテープの剥離強度については、IEC60286-3に準拠
COVER TAPE PEEL FORCE IS DEFINED
BY IEC60286-3

5.材料 (MATERIAL)
 キャリアテープ (CARRIER TAPE): ポリプロピレン (POLYPROPYLENE)
 トップテープ (TOPTAPE): PET, PE, PEF
 リール (REEL): ポリスチレン (PS) <リサイクル材を含む>
 POLYSTYREN (PS) <RECYCLE MATERIAL CONTAINED>

6. 本製品は乾燥剤入り、ハイバリア梱包仕様である。
THIS PRODUCT IS HIGH BARRIER PACKAGE
WITH DESICCANT.

24	29.4	25.4	15	11.4	18.3	52271-1169	11
			14	10.4	17.3	52271-1069	10
			12	8.4	15.3	52271-0869	8
			11	7.4	14.3	52271-0769	7
			10	6.4	13.3	52271-0669	6
			9	5.4	12.3	52271-0569	5
			8	4.4	11.3	52271-0469	4
キャリアテープ幅 CARRIER TAPE WIDTH	F	D	(C)	(B)	(A)	MATERIAL NO.	極 数 C/KT

REVISED	EC NO: J2010-2474 DRAWN: YUHASAGAWA 2010/06/08 CHKD: K. TOYODA 2010/06/08 APPR: KMORI KAWA 2010/06/09	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
			10 UNDER	± 0.2	DRAWN BY M. UMEDA	DATE 2005/03/08	TITLE EMBOSSD TAPE PACKAGE FOR 52271-**29 -LEAD FREE-			
			10 OVER 30 UNDER	± 0.25	CHECKED BY K. TOYODA	DATE 2005/03/08				
			30 OVER	± 0.3	APPROVED BY N. UKITA	DATE 2005/03/08				
			ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-52271-039		1 OF 4	
			REV	G	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

10 9 8 7 6 5 4 3 2 1

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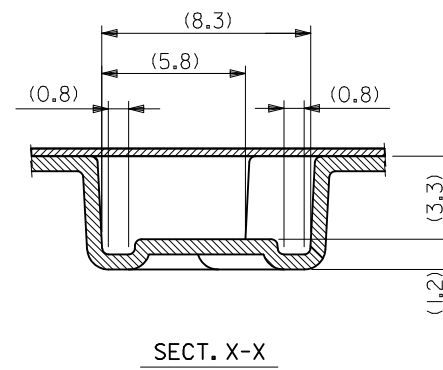
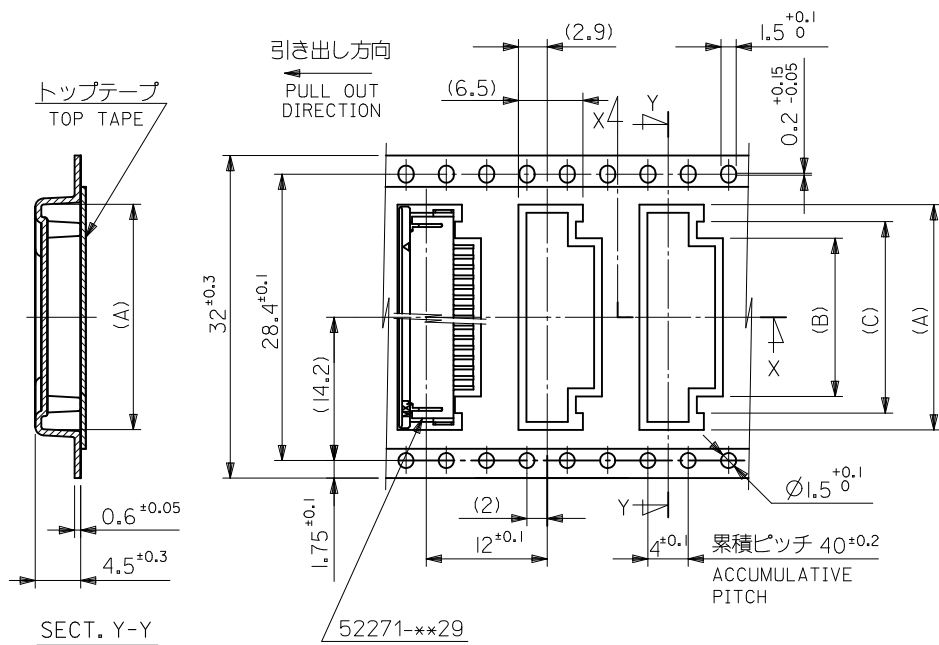
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32	37.4	33.4	20	16.4	23.35	52271-1669	16
			19	15.4	22.35	52271-1569	15
			18	14.4	21.35	52271-1469	14
			17	13.4	20.35	52271-1369	13
			16	12.4	19.35	52271-1269	12
キャリアテープ幅 CARRIER TAPE WIDTH	F	D	(C)	(B)	(A)	MATERIAL NO.	極数 CKT.

REVISED EC NO. J2010-2474 DRWN: YU HASEGAWA 2010/06/08 CHKD: K. TOYODA 2010/06/08 APPR: KMORI KAWA 2010/06/09	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY M. UMEDA	DATE 2005/03/08	TITLE EMBOSSED TAPE PACKAGE FOR 52271-**-29 -LEAD FREE-				
		10 OVER 30 UNDER	± 0.25	CHECKED BY K. TOYODA	DATE 2005/03/08					
		30 OVER	± 0.3	APPROVED BY N. UKITA	DATE 2005/03/08	MOLEX MOLEX INCORPORATED				
		ANGULAR ±3 °		MATERIAL NO.			DOCUMENT NO.			SHEET NO.
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE			SD-52271-039			2 OF 4
	REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								

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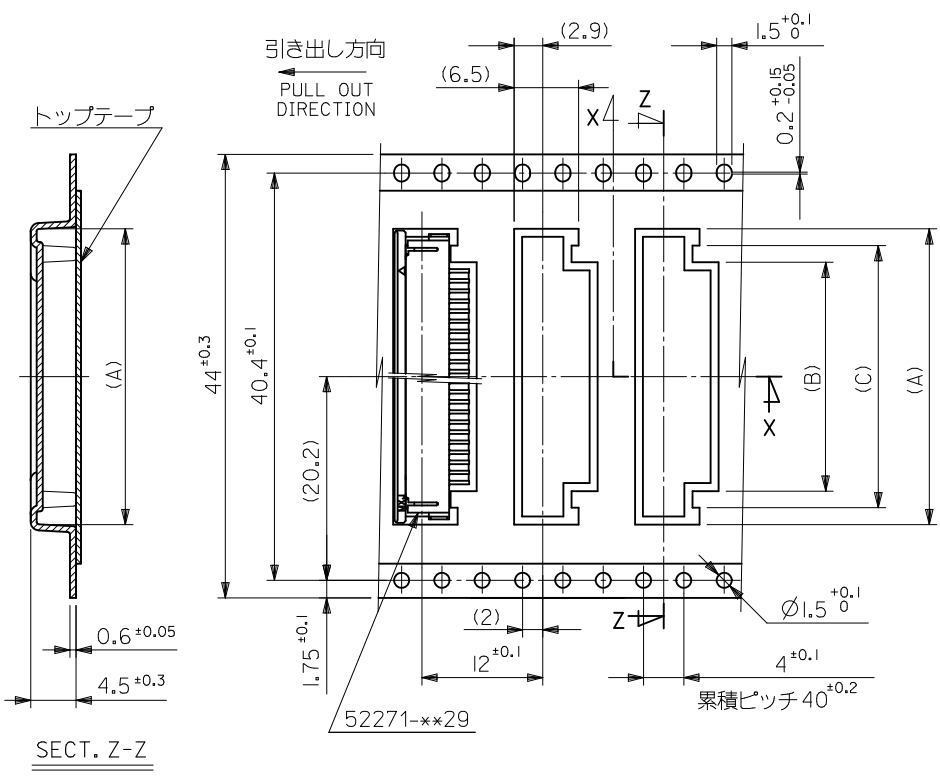
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44	49.4	45.4	31	27.4	34.35	52271-2769	27
			29	25.4	32.35	52271-2569	25
			28	24.4	31.35	52271-2469	24
			26	22.4	29.35	52271-2269	22
			25	21.4	28.35	52271-2169	21
			24	20.4	27.35	52271-2069	20
			23	19.4	26.35	52271-1969	19
			22	18.4	25.35	52271-1869	18
			21	17.4	24.35	52271-1769	17
キャリアテープ幅	F	D	(C)	(B)	(A)	MATERIAL NO.	極数

REVISED EC NO: J2010-2474 DRWN: YUHASEGAWA 2010/06/08 CHKD: K. TOYODA 2010/06/08 APPR: KMORI KAWA 2010/06/09	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION					
		10 UNDER	± 0.2	DRAWN BY	DATE	TITLE									
		10 OVER 30 UNDER	± 0.25	CHECKED BY	DATE	EMBOSSD TAPE PACKAGE FOR 52271-**29 -LEAD FREE-									
		30 OVER	± 0.3	APPROVED BY	DATE										
		ANGULAR ± 3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.							
G		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-52271-039		3 OF 4							
				SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									

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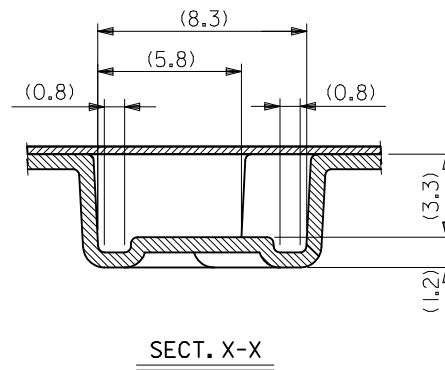
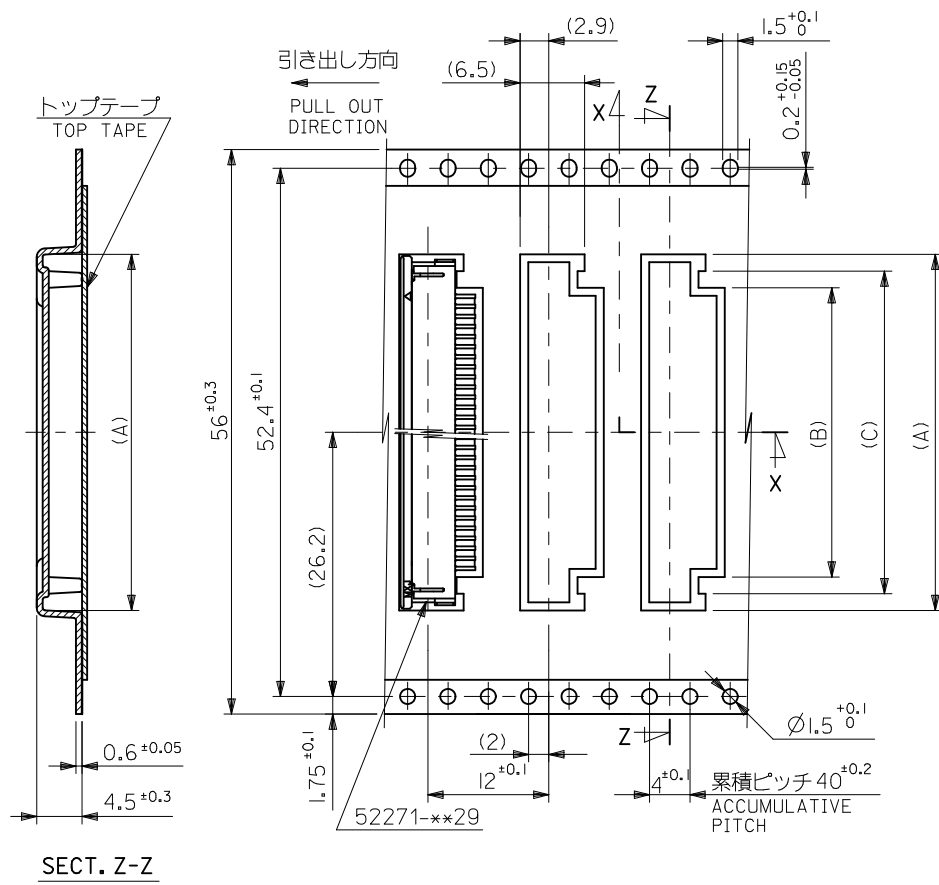
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56	61.4	57.4	34	30.4	37.35	52271-3069	30
			32	28.4	35.35	52271-2869	28
キャリアテープ幅 CARRIER TAPE WIDTH			(C)	(B)	(A)	MATERIAL NO.	極数 CKT.

REVISED	EC NO: J2010-2474 DRWNG: YU HASEGAWA CHKD: K. TOYODA APPR: KMORI KAWA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			10 UNDER	± 0.2	M. UMEDA	2005/03/08	TITLE EMBOSSED TAPE PACKAGE FOR 52271-**29 -LEAD FREE-				
			10 OVER 30 UNDER	± 0.25	K. TOYODA	2005/03/08					
			30 OVER	± 0.3	APPROVED BY N. UKITA	2005/03/08					
			ANGULAR ±3 °		MATERIAL NO.		MOLEX MOLEX INCORPORATED		DOCUMENT NO.		SHEET NO.
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-52271-039		4 OF 4		
			G	REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

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Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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